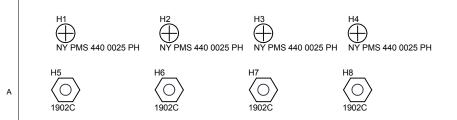


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PCB Number: PMP10545 PCB Rev:

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PCB LOGO Texas Instruments

Label Table						
Variant	Label Text					
001						

ZZ2 Assembly Note These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3
Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

1

ZZ4 Assembly Note These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

					Designed for: Public Relea	Mod. Date: 4/20/2015	
					Project Title: LM5160 Fly-E	Buck-Boost	LIA TEXAS
				Number: PMP10545 Rev: 5	Sheet Title:		
T	exas Instruments and/or its licensors	do not warrant the accuracy or completeness of this specification or any	r information contained therein. Texas Instruments and/or its licensors do r	not SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 2 of 2	
w	arrant that this design will meet the s	pecifications, will be suitable for your application or fit for any particular	purpose, or will operate in an implementation. Texas Instruments and/or it	s Drawn By:	File: PMP10545_Hardware	ANSI-B.SchDoc Size: B	http://www.ti.com
lic	censors do not warrant that the desig	n is production worthy. You should completely validate and test your des	sign implementation to confirm the system functionality for your application	. Engineer: David Baba/Hrag Kasparia	rContact: http://www.ti.com	/support	© Texas Instruments 2014
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